by dissolving solid material in a supercritical fluid solution at elevated pressure and then rapidly expanding the solution through an orifice into a region of relatively low pressure; (see also U.S. Patent Nos. 4,970,093 and 5,374,305).--

MARKED-UP COPY OF SPECIFICATION AMENDMENTS

At page 3, lines 3 through 16, delete the paragraph and replace with the following paragraph:

--Rapid expansion of a supercritical fluid typically results in very large supersaturation ratios (Mohamed *et al.*, 35 AICHE Journal 325 - 328, 1989). It is also reported that crystals of various solid substances can be grown in good morphological quality by dissolving the solid substance in a subcritical or supercritical fluid at high pressure, and then slowly, and gradually decreasing the pressure while minimizing heat transfer between the solid-solution system and its environment (See, e.g., U.S. Patent No. 4,512,846). RESS re-crystallization techniques have been used to recrystallize a number of compounds, including pharmaceutical preparations (See, e.g., U.S. Patent No. 4,978,752 with respect to crystals of cephem hydrochloride). Such technique has also been used to deposit coatings and films on substrates (See, e.g., U.S. Patent No. 4,582,731) which discloses methods for solid film deposition and fine powder formation by dissolving solid material in a supercritical fluid solution at elevated pressure and then rapidly expanding the solution through an orifice into a region of relatively low pressure; (see also U.S. Patent Nos. 4,970,093 and ~~5,734,305~~5,374,305).--

REMARKS

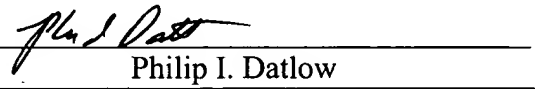
The specification has been amended to correct a typographical error in a patent number referred to on page 3.

Respectfully submitted,

Philip I. Datlow
Reg. No. 41,482

Patent Department
Boehringer Ingelheim Corp.
900 Ridgebury Road
P.O. Box 368
Ridgefield, CT 06877
Tel: (203) 798-4542
Date: June 29, 2001

Certificate of Mailing
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to:
Assistant Commissioner For Patents
Washington, DC 20231
on June 29, 2001.



Philip I. Datlow